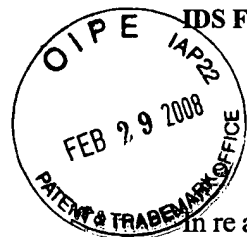


Form PTO-1449
U.S. Application No.: 10/725,933
Attorney Docket No.: HK9225US
IDS Filed: February 26, 2008



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE CITATION

In re application of: Yang et al.

Confirmation No.: 4487

Serial No.: 10/725,933

Group No.: 2891

Filed: December 3, 2003

Examiner: David A. Zarneke

For: FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Other Documents (Inc. Author, Title, Date, Pertinent Pages, Etc.)

Examiner

Initials **Document**

_____ Yuan et al., "Design, Experiment and Analysis of the Solder on Rubber (SOR) Structure of WLCSP, 7th Int. Conf. on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems, EuroSimE 2006.

Examiner:

Date Considered:

****Examiner:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.